

Dual Output Low ESR Cap. Low-Dropout 600mA Linear Regulator

FEATURES

- Up to 600mA Output Current for Each LDO.
- Low Quiescent Current : 50 μ A (V_{OUT1} and V_{OUT2} Enable Mode).
- Low Dropout : 470mV at 600mA Load Current and 3.3V Output Voltage.
- High PSRR : 70dB at 1kHz.
- Independent Shutdown Controls.
- Current Limit and Thermal Protection.
- SOT-23-6, SOP-8 Package.

APPLICATIONS

- Cellular Phones.
- PDAs.
- Digital Still Cameras.
- Portable Consumer Equipments.

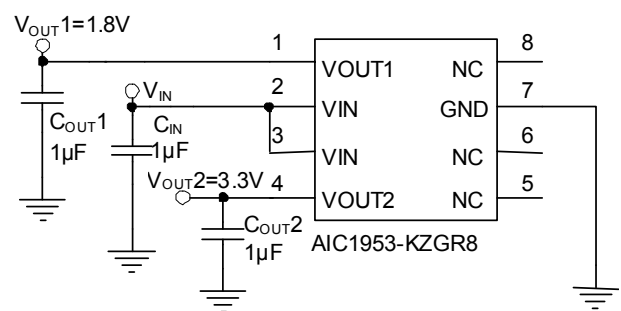
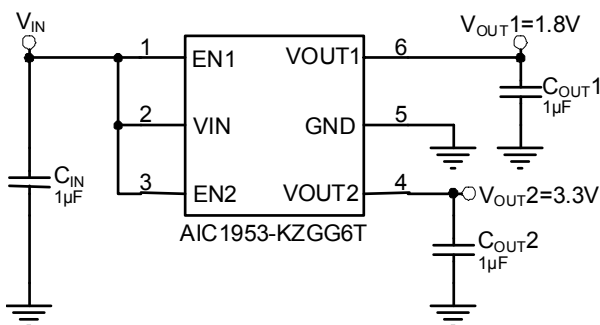
DESCRIPTION

The AIC1953 is a dual output linear regulator in a SOT-23-6 and SOP-8 package. It is optimized for low ESR ceramic capacitors operation and up to 600mA continuous current on each output.

The AIC1953 offers high precision output voltage of $\pm 2\%$. At 600mA load current, a 470mV dropout is performed when output voltage is equal to 3.3V. The quality of low quiescent current and low dropout voltage makes this device ideal for battery power applications. The high ripple rejection and low noise of the AIC1953 provide enhanced performances for critical applications such as cellular phones, and PDAs.

The AIC1953 includes current limit and thermal shutdown protection. Each of the output is controlled independently.

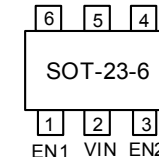
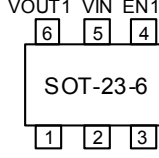
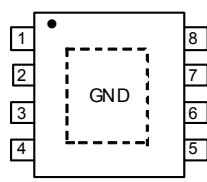
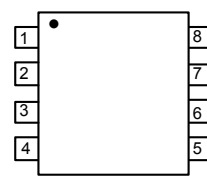
TYPICAL APPLICATION CIRCUIT



ORDERING INFORMATION

AIC1953-XXXXXXXXXX

PACKING TYPE TR: TAPE & REEL BG: BAG	PACKAGE TYPE G6T: SOT-23-6 G6A: SOT-23-6 R8: SOP-8 Exposed Pad (Heat Sink) S8: SOP-8																						
G: GREEN PACKAGE																							
OUTPUT2 VOLTAGE:																							
	<table border="1"> <thead> <tr> <th></th> <th>VOUT2</th> </tr> </thead> <tbody> <tr><td>A</td><td>0.8V</td></tr> <tr><td>:</td><td>:</td></tr> <tr><td>:</td><td>:</td></tr> <tr><td>Z</td><td>3.3V</td></tr> <tr><td>3</td><td>2.85V</td></tr> <tr><td>4</td><td>3.4V</td></tr> <tr><td>5</td><td>3.5V</td></tr> <tr><td>6</td><td>3.6V</td></tr> <tr><td>7</td><td>3.7V</td></tr> <tr><td>8</td><td>3.8V</td></tr> </tbody> </table>		VOUT2	A	0.8V	:	:	:	:	Z	3.3V	3	2.85V	4	3.4V	5	3.5V	6	3.6V	7	3.7V	8	3.8V
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PACKAGE TYPE	PIN CONFIGURATION
G6T (SOT-23-6)	FRONT VIEW VOUT1 GND VOUT2 
G6A (SOT-23-6)	FRONT VIEW VOUT1 VIN EN1 
R8 (SOP-8)	SOP-8 (R8) Exposed Pad (Heat Sink) 1: VOUT1 2: VIN 3: VIN 4: VOUT2 5: NC 6: NC 7: GND (TAB) 8: NC TOP VIEW 
S8 (SOP-8)	SOP-8 (S8) 1: VOUT1 2: VIN 3: VIN 4: VOUT2 5: GND 6: GND 7: GND 8: GND TOP VIEW 

(Internally set VOUT1 · VOUT2 and PACKAGE TYPE, refer to the “designator xxxxxx” table below. For other combinations, a unit of 0.1V within 0.8~3.8V, additional voltage versions and package type are available on demand.)

Example: AIC1953-KEGR8TR

→ Vout1 = 1.8V, Vout2 = 1.2V, with GR8 type pin configuration in SOP-8 Exposed Pad (Heat Sink) Green package and TAPE & REEL packing.

AIC1953-ZKGS8TR

→ Vout1 = 3.3V, Vout2 = 1.8V, with GS8 type pin configuration in SOP-8 Green package and TAPE & REEL packing.

●Designator xxxxxx

Designator	Output Voltage		Designator	Output Voltage	
	VOUT1	VOUT2		VOUT1	VOUT2
xxxxxx WWGG6T WWGG6A WWGR8 WWGS8	3.0	3.0	xxxxxx KEGG6T KEGG6A KEGR8 KEGS8	1.8	1.2
xxxxxx EZGG6T EZGG6A EZGR8 EZGS8	1.2	3.3	xxxxxx ZUGG6T ZUGG6A ZUGR8 ZUGS8	3.3	2.8
xxxxxx ZKGG6T ZKGG6A ZKGR8 ZKGS8	3.3	1.8	xxxxxx ZWGG6T ZWGG6A ZWGR8 ZWGS8	3.3	3.0
xxxxxx UHGG6T UHGG6A UHGR8 UHGS8	2.8	1.5	xxxxxx ZZGG6T ZZGG6A ZZGR8 ZZGS8	3.3	3.3
xxxxxx KUGG6T KUGG6A KUGR8 KUGS8	1.8	2.8	xxxxxx KZGG6T KZGG6A KZGR8 KZGS8	1.8	3.3

●SOT-23-6 Marking

Part No.	Package Code	Package Type	Marking	Output Voltage
AIC1953-xx	GG6T	SOT-23-6	GVxxG	1st x = Vout1, 2nd x = Vout2 x=A, B, ..., Y, Z, 3~8
AIC1953-xx	GG6A	SOT-23-6	GUxxG	(A=0.8V, B=0.9V,.....Y=3.2V, Z=3.3V, 0.1V a step, 3=2.85V, 4=3.4V, 5=3.5V, 6=3.6V, 7=3.7V, 8=3.8V)

■ ABSOLUTE MAXIMUM RATINGS

Input Voltage	7V
EN Pin Voltage.....	7V
Operating Ambient Temperature Range T_A	-40°C~85°C
Operating Maximum Junction Temperature T_J	150°C
Storage Temperature Range T_{STG}	-65°C~150°C
Lead Temperature (Soldering 10 Sec.).....	260°C
Thermal Resistance Junction to Case	
SOT-23-6	115°C/W
SOP-8 (Exposed Pad)	15°C /W
SOP-8.....	40°C /W
Thermal Resistance Junction to Ambient	
SOT-23-6	250°C/W
SOP-8 (Exposed Pad).....	60°C /W
SOP-8.....	160°C /W

(Assume no Ambient Airflow, no Heat sink)

Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

* The package is placed on a two layers PCB with 2 ounces copper and 2 square inch, connected by 8 vias

ELECTRICAL CHARACTERISTICS
($V_{IN} = V_{OUT} + 1V$, $V_{EN1}=V_{EN2}= V_{IN}$, $T_J=25^{\circ}C$, unless otherwise specified) (Note 1)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Input Voltage (Note 2)		V_{IN}	1.6		6.0	V	
Output Voltage Tolerance	$V_{IN}= 6.0V$, $I_{OUT} = 1mA$	V_{OUT}	-2		2	%	
Continuous Output Current		I_{OUT}	600			mA	
Quiescent Current	$V_{EN2} = V_{EN1} = V_{IN}$	I_Q		50	80	μA	
GND Pin Current	$I_{OUT1} = 600mA$ & $I_{OUT2} = 600mA$, $V_{EN2} = V_{EN1} = V_{IN}$	I_{GND}		55	80	μA	
Standby Current	$V_{EN1}=V_{EN2}= 0$	I_{STBY}			0.1	μA	
Output Current Limit	$V_{OUT} = GND$	I_{IL}	650	950		mA	
Dropout Voltage	$I_{OUT} = 600mA$	V_{DROP}			710	850	mV
					580	700	
					470	560	
Line Regulation	$V_{IN} = V_{OUT} + 1V$ to 6V	ΔV_{LIR}		3	16	mV	
Load Regulation	$I_{OUT} = 1mA$ to 600mA	ΔV_{LOR}		2	10	mV	
Ripple Rejection	$f=1kHz$, Ripple=0.5Vp-p,	PSRR		70		dB	
Output Noise Voltage	$f= 10\sim 100KHz$			24		μV_{rms}	
Temperature Coefficient		TC		50		ppm/ $^{\circ}C$	
Thermal Shutdown Temperature	$V_{IN} = V_{OUT} + 1V$			150		$^{\circ}C$	
Thermal Shutdown Hysteresis				35		$^{\circ}C$	
EN Pin SPECIFICATIONS							
EN Pin Current	$V_{EN1} = V_{EN2} = V_{IN}$	I_{EN}			0.1	μA	
Shutdown Exit Delay Time		Δt		100		μS	
Max Output Discharge Resistance to GND during shutdown		$RDSON_{CLMP}$		20		Ω	
EN Input Threshold	Output ON	V_{ENH}	1.6			V	
	Output OFF	V_{ENL}			0.25		

Note 1: Specifications are production tested at $T_A=25^{\circ}C$. Specifications over the $-40^{\circ}C$ to $85^{\circ}C$ operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).

Note 2: $V_{IN}(min)$ is the higher value of $V_{out} + \text{Dropout Voltage}$ or 1.6V.

TYPICAL PERFORMANCE CHARACTERISTICS

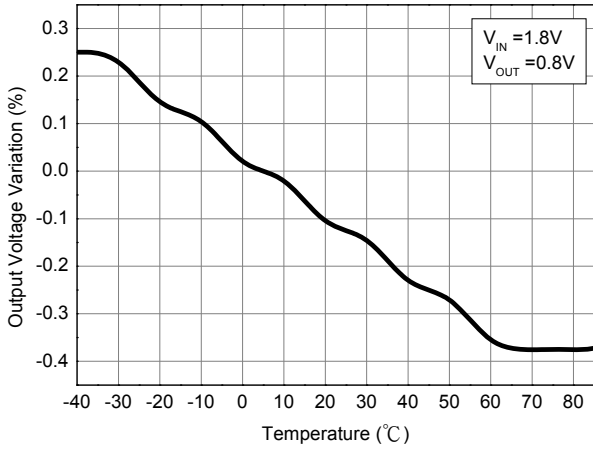


Fig.1 Output Voltage Variation vs. Temperature

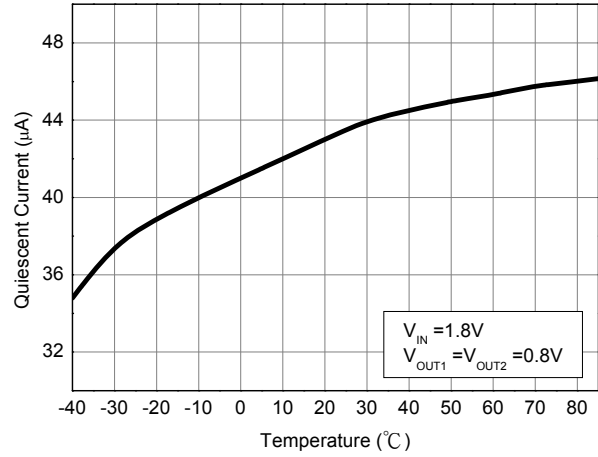


Fig.2 Dual LDO Quiescent Current vs. Temperature

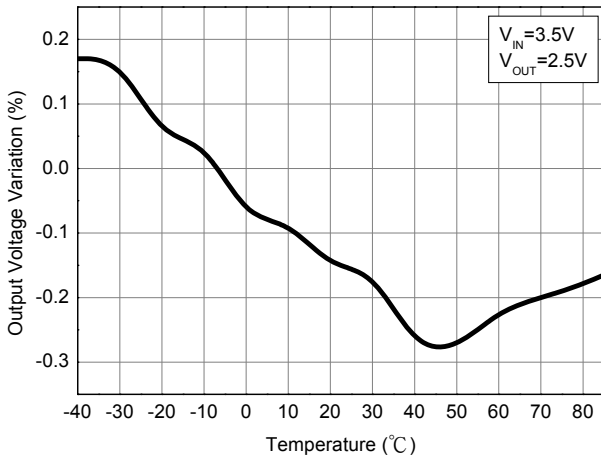


Fig.3 Output Voltage Variation vs. Temperature

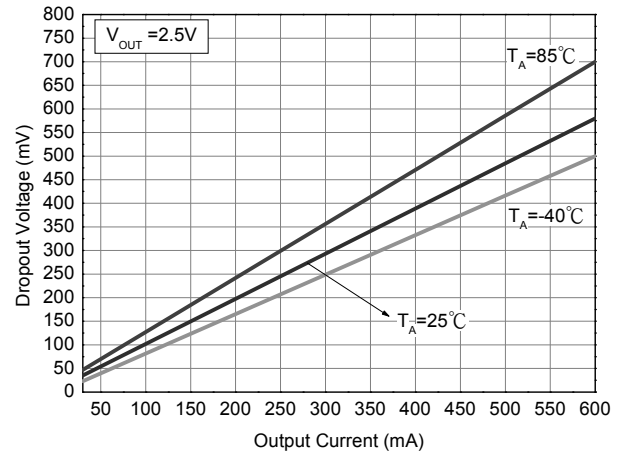


Fig.4 Dropout Voltage vs. Output Current

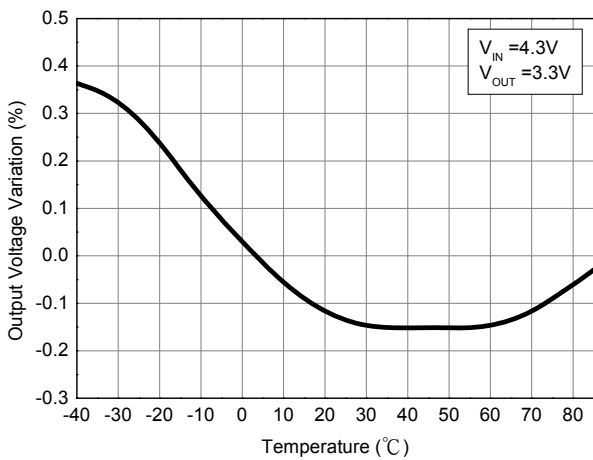


Fig.5 Output Voltage Variation vs. Temperature

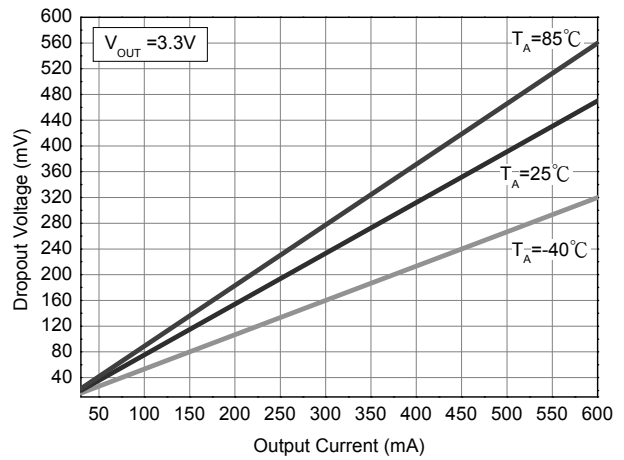


Fig.6 Dropout Voltage vs. Output Current

TYPICAL PERFORMANCE CHARACTERISTICS

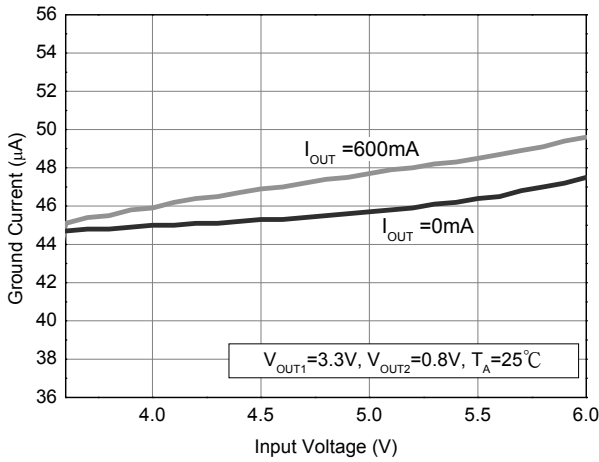


Fig.7 Dual LDO Quiescent Current and Ground Current vs. Input Voltage

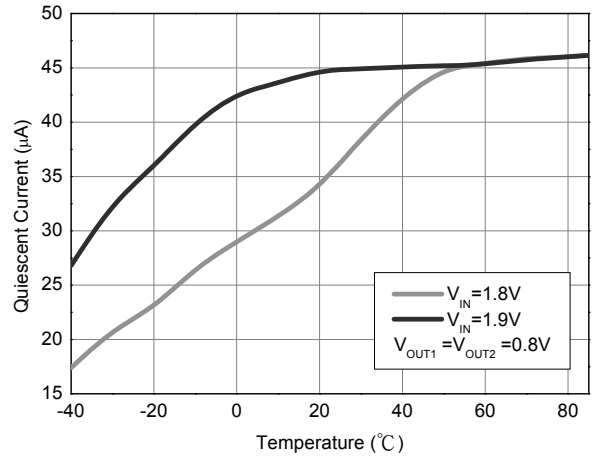


Fig.8 Quiescent Current vs. Temperature.

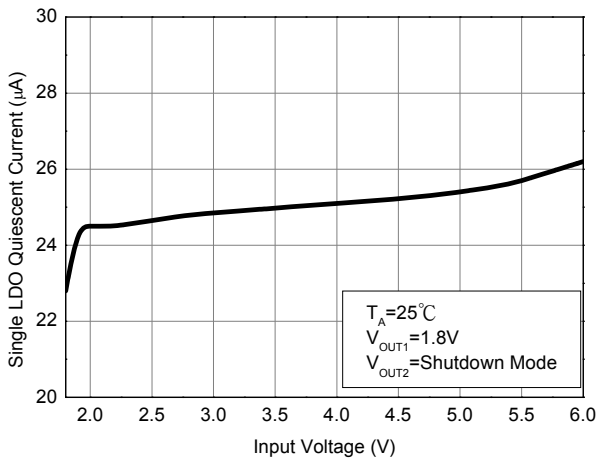


Fig.9 Single LDO Quiescent Current vs. Input Voltage

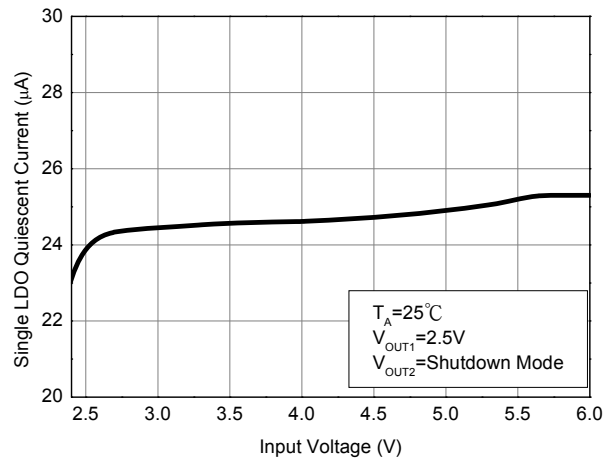


Fig.10 Single LDO Quiescent Current vs. Input Voltage

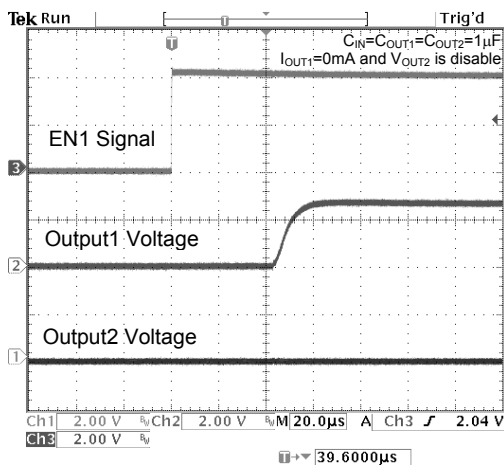


Fig.11 Start Up Waveform at $V_{IN}=3.8V$, $V_{OUT1}=2.8V$ and $V_{OUT2}=1.8V$

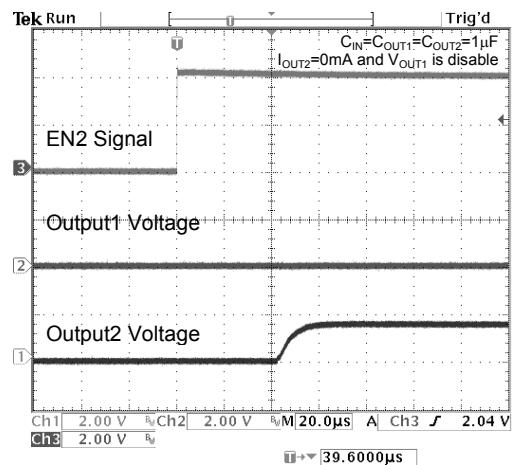


Fig.12 Start Up Waveform at $V_{IN}=3.8V$, $V_{OUT1}=2.8V$ and $V_{OUT2}=1.8V$

TYPICAL PERFORMANCE CHARACTERISTICS

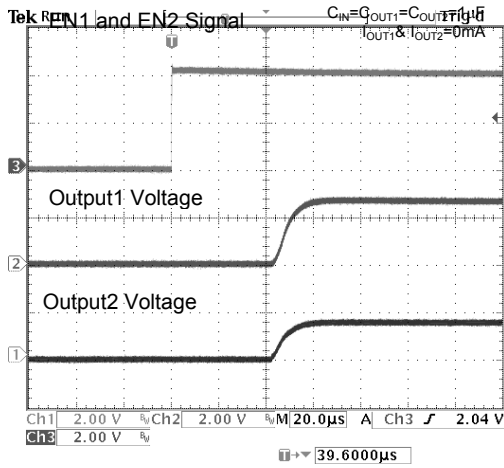


Fig.13 Start Up Waveform at $V_{IN}=3.8V$, $V_{OUT1}=2.8V$ and $V_{OUT2}=1.8V$

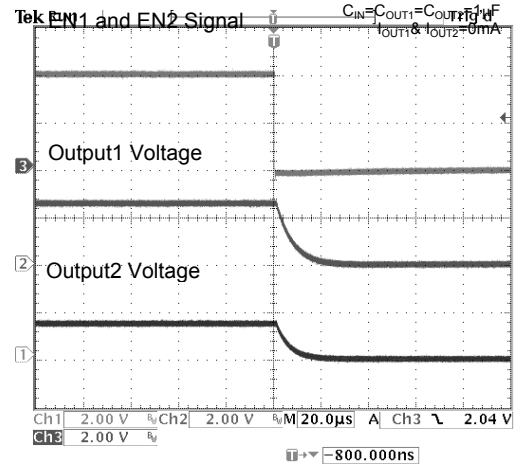


Fig.14 Shutdown Waveform at $V_{IN}=3.8V$, $V_{OUT1}=2.8V$ and $V_{OUT2}=1.8V$

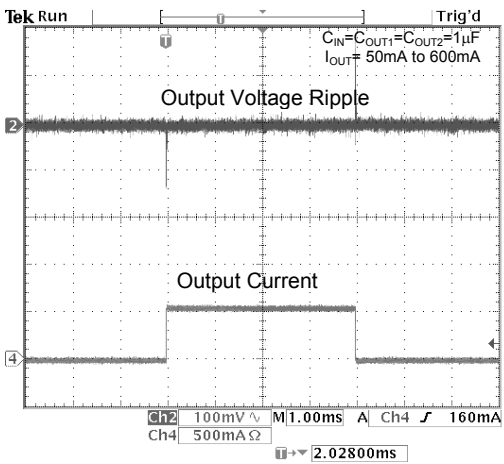


Fig.15 Load Transient Response at $V_{IN}=2.8V$, $V_{OUT}=0.8V$

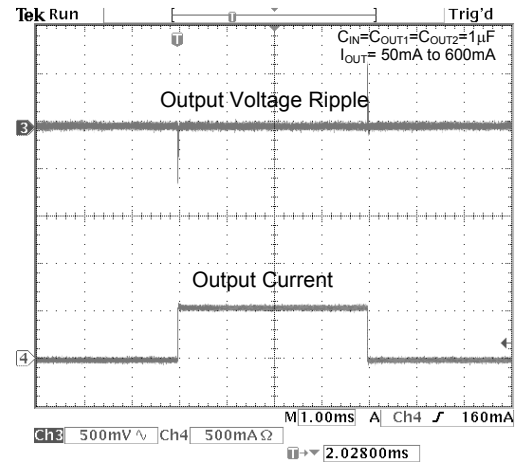


Fig.16 Load Transient Response at $V_{IN}=4.8V$, $V_{OUT}=3.8V$

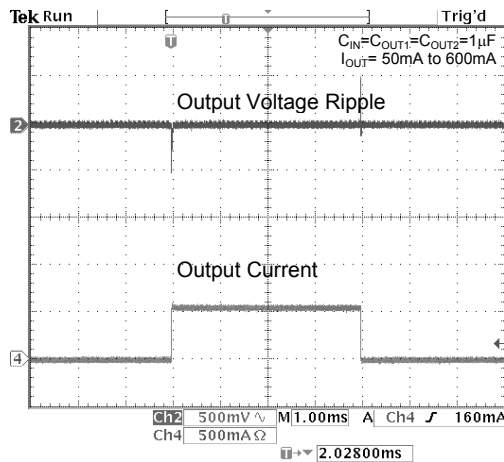


Fig.17 Load Transient Response at $V_{IN}=3.8V$, $V_{OUT}=2.8V$

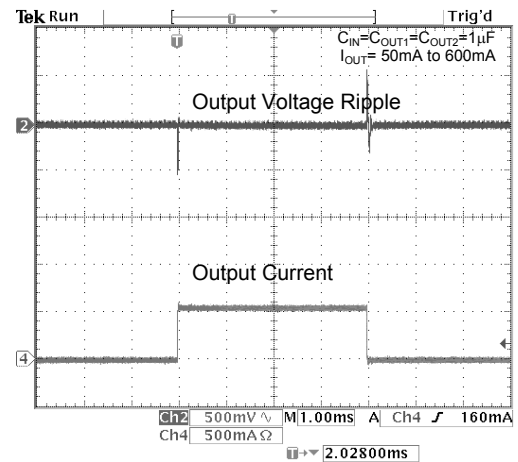


Fig.18 Load Transient Response at $V_{IN}=4.3V$, $V_{OUT}=3.3V$

TYPICAL PERFORMANCE CHARACTERISTICS

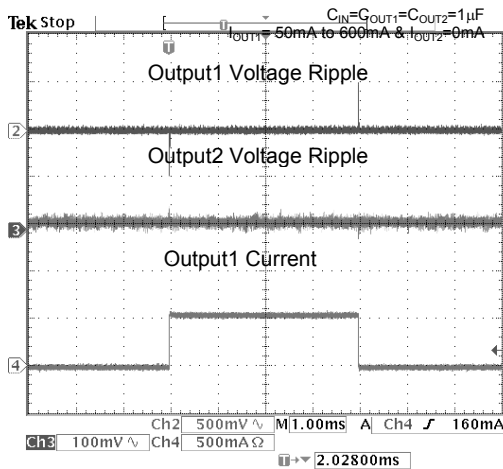


Fig.19 Cross Talk at $V_{IN}=4.3V$, $V_{OUT1}=2.8V$ and $V_{OUT2}=3.3V$

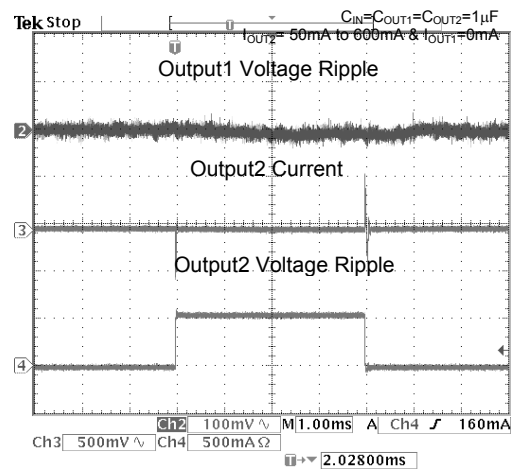


Fig.20 Cross Talk at $V_{IN}=4.3V$, $V_{OUT1}=2.8V$ and $V_{OUT2}=3.3V$

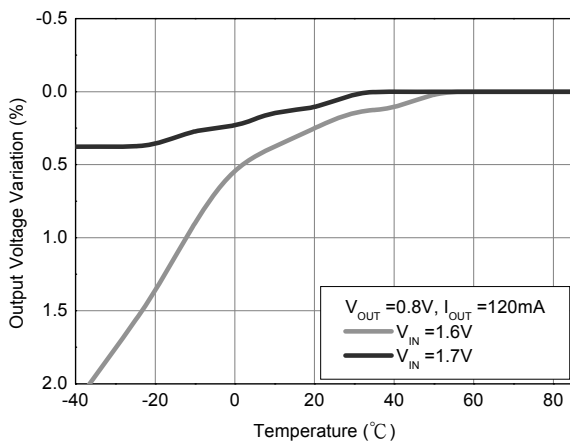


Fig.21 Output Voltage Variation vs. Temperature.

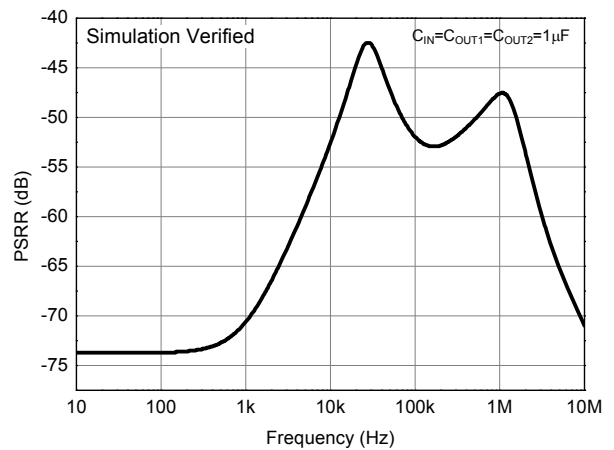
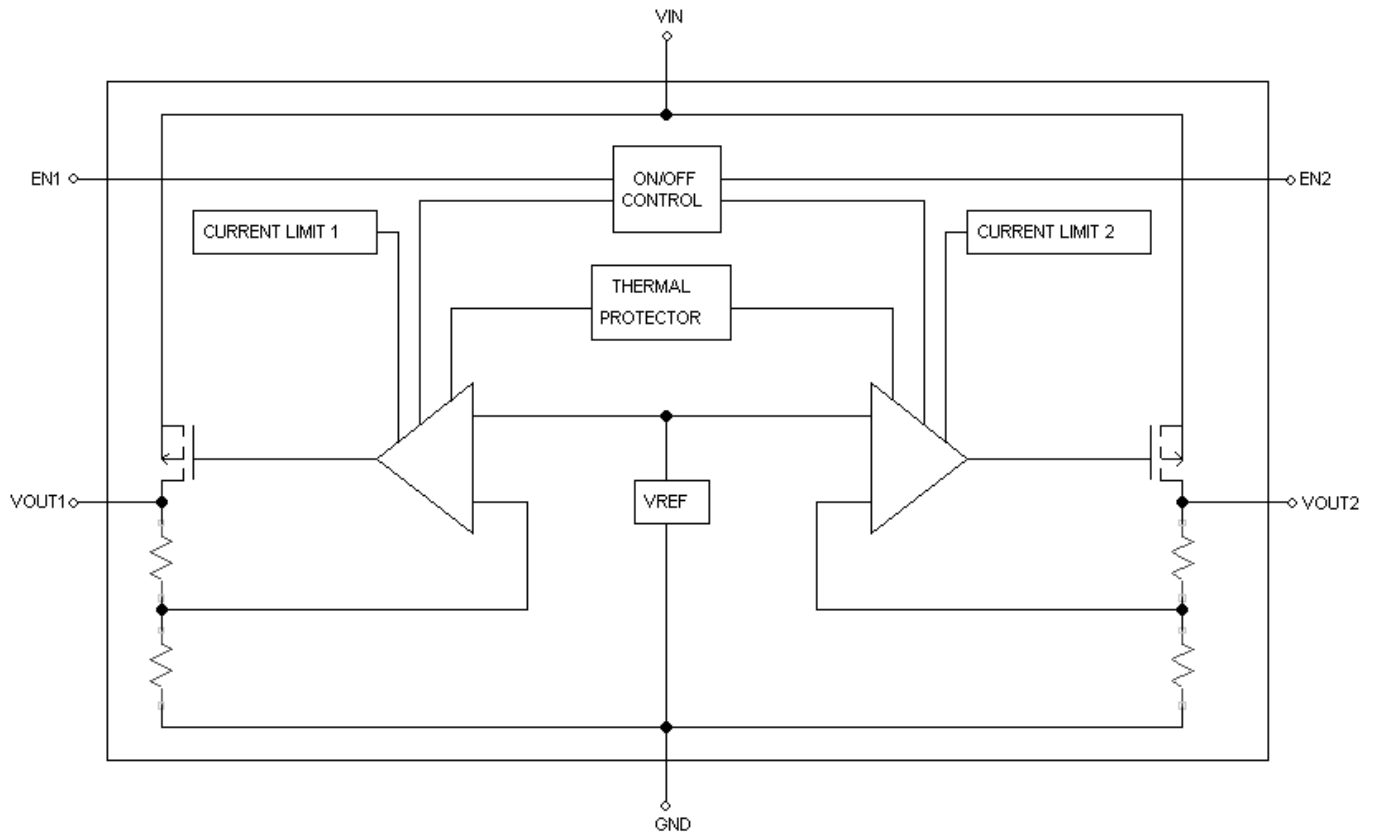


Fig.22 PSRR at $V_{IN}=2.5V$, $V_{OUT}=1.0V$ and $I_{OUT}=10mA$.

■ BLOCK DIAGRAM



■ PIN DESCRIPTION

VIN PIN - Power input.

GND PIN - Ground.

EN1 PIN(SOT-23-6) - Output 1 ON/OFF controller. This pin isn't allowed to float.

EN2 PIN(SOT-23-6) - Output 2 ON/OFF controller. This pin isn't allowed to float.

VOUT1 PIN - Output 1.

VOUT2 PIN - Output 2.

■ APPLICATION INFORMATION

The AIC1953 is a low-dropout, low quiescent-current, dual-output linear regulator for battery power applications. These parts are available with preset output voltages ranging from 0.8V to 3.8V, and the parts can supply loads up to 600mA.

SHUTDOWN

The AIC1953 has two independent shutdown control inputs (EN1 and EN2). By connecting EN1 pin to ground, output1 can be shut down. By connecting EN2 pin to ground, output2 can be shut down. By connecting both of EN1 pin and EN2 pin to ground, the AIC1953 can be shut down to reduce the supply current to 0.1 μ A.

CURRENT LIMIT

The AIC1953 includes two independent current limiters, which monitor and control the maximum output current. If the output is overloaded or shorted to ground, this can protect the device from being damaged.

THERMAL PROTECTION

The AIC1953 includes a thermal-limiting circuit, which is designed to protect the device against overload condition. When the junction temperature exceeds $T_J=150^{\circ}\text{C}$, the thermal-limiting circuit turns off the pass transistors and allows the IC to cool. For continuous load condition, maximum rating of junction temperature must not be exceeded.

INPUT-OUTPUT CAPACITORS

Linear regulators require input and output capacitors to maintain stability. Input capacitor at 1 μ F with a 1 μ F ceramic output capacitor for each regulator is

recommended. To avoid oscillation, it is recommended to follow the figure of “Region of Stable C_{OUT} ESR vs. Load Current” to choose proper capacitor specifications.

When choosing the input and output ceramic capacitors, X5R and X7R types are recommended because they retain their capacitance over wider ranges of voltage and temperature than other types.

POWER DISSIPATION

The maximum power dissipation of AIC1953 depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

The power dissipation across the device is

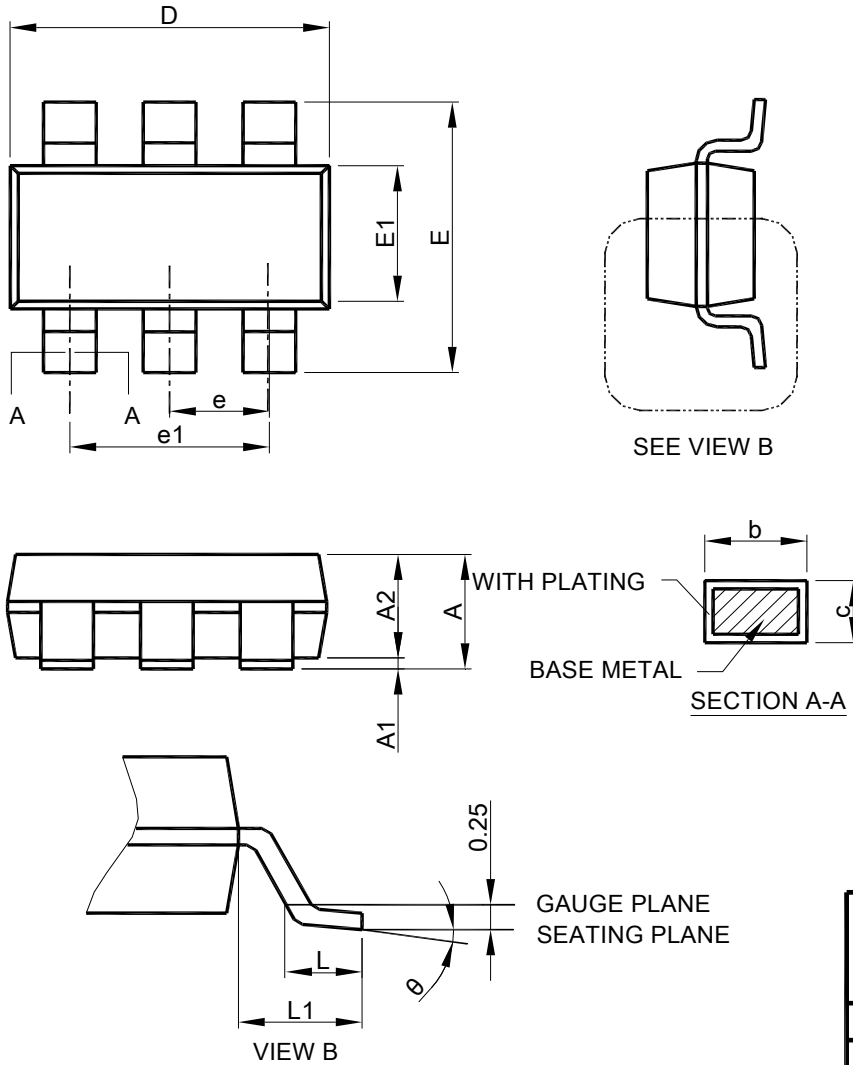
$$P = I_{\text{OUT1}} (V_{\text{IN}} - V_{\text{OUT1}}) + I_{\text{OUT2}} (V_{\text{IN}} - V_{\text{OUT2}})$$

The maximum power dissipation is:

$$P_{\text{MAX}} = \frac{(T_{\text{J-max}} - T_{\text{A}})}{R\theta_{\text{JA}}}$$

Where $T_{\text{J-max}}$ is the maximum allowable junction temperature (150 $^{\circ}\text{C}$), and T_{A} is the ambient temperature suitable in application.

As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature.

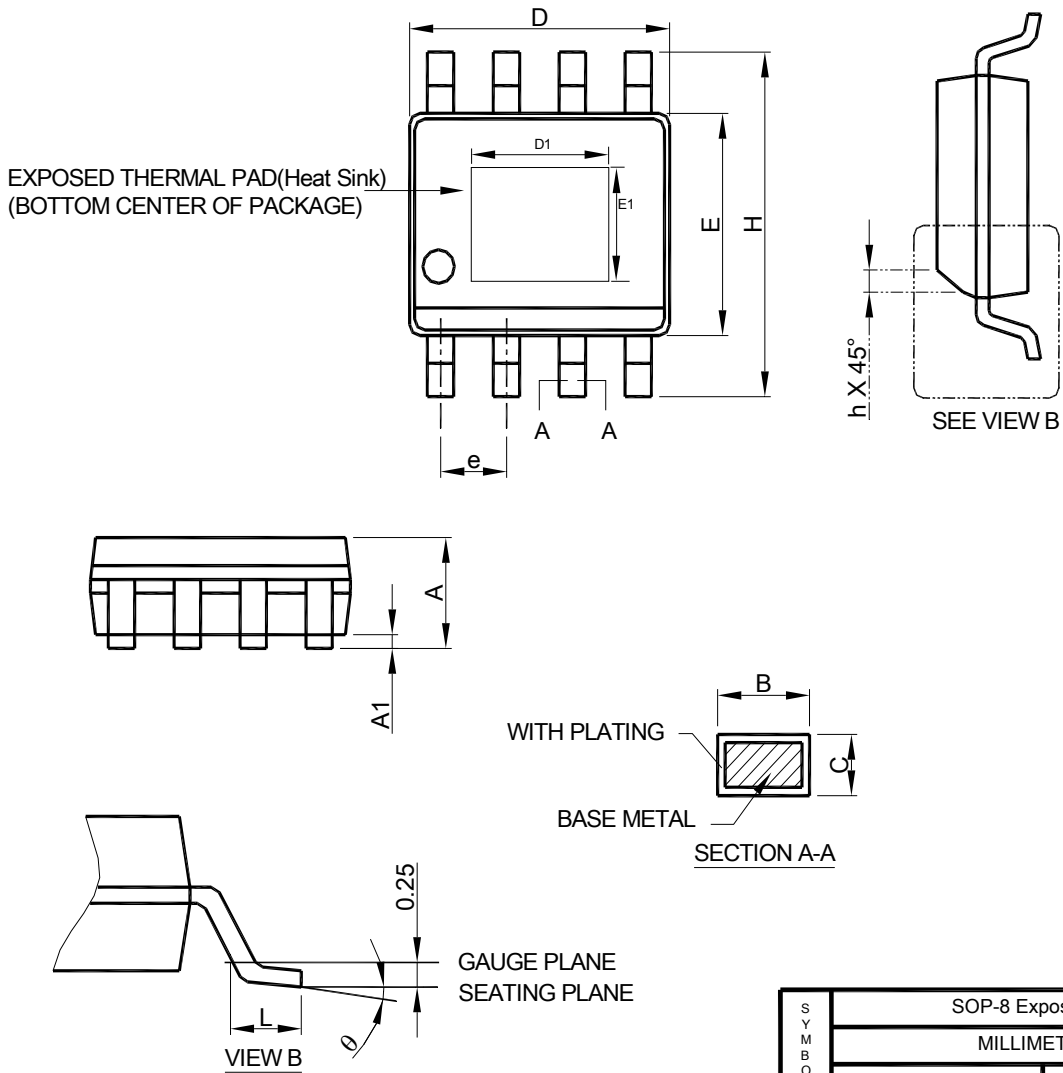
PHYSICAL DIMENSIONS
SOT-23-6 PACKAGE OUTLINE DRAWING


Note : 1. Refer to JEDEC MO-178AB.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.
3. Dimension "E1" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

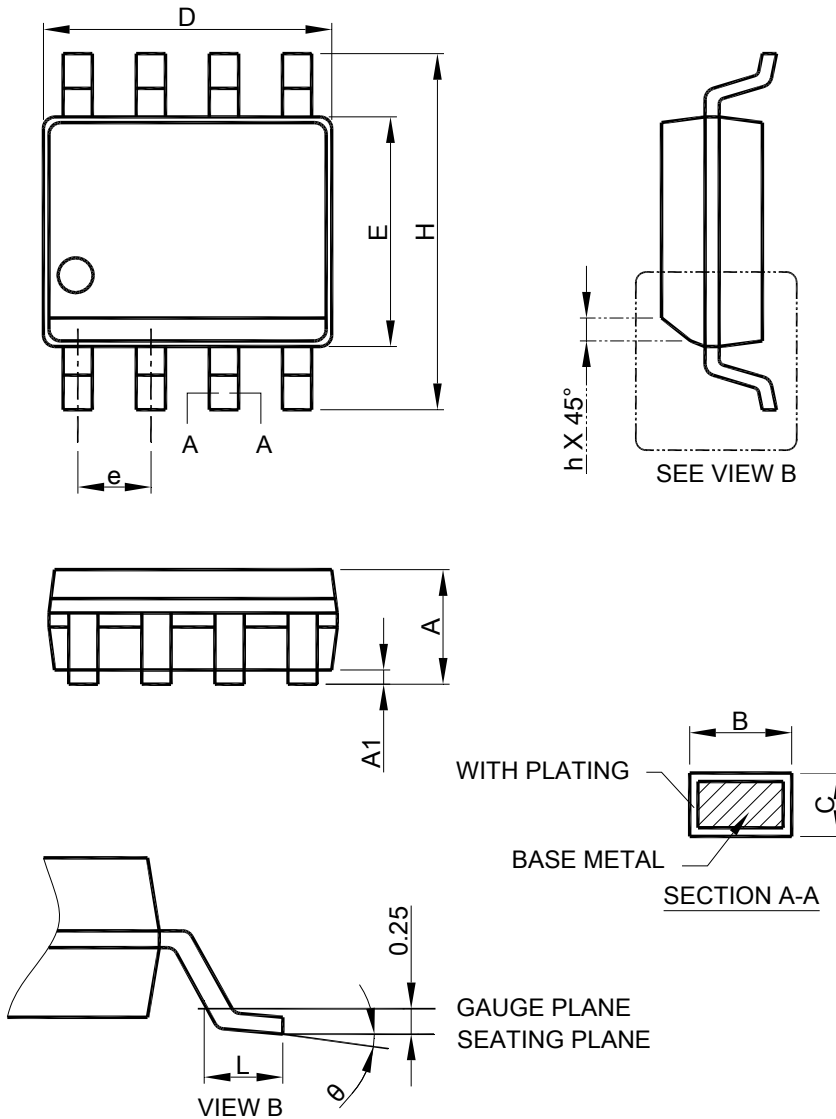
SYMBOL	SOT-23-6	
	MILLIMETERS	
	MIN.	MAX.
A	0.95	1.45
A1	0.00	0.15
A2	0.90	1.30
b	0.30	0.50
c	0.08	0.22
D	2.80	3.00
E	2.60	3.00
E1	1.50	1.70
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60
L1	0.60 REF	
θ	0°	8°

● SOP-8 Exposed Pad (Heat Sink) PACKAGE OUTLINE DRAWING



- Note : 1. Refer to JEDEC MS-012E.
 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side .
 3. Dimension "E" does not include inter-lead flash or protrusions.
 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

SYMBOL	SOP-8 Exposed Pad(Heat Sink)	
	MILLIMETERS	
	MIN.	MAX.
A	1.35	1.75
A1	0.00	0.15
B	0.31	0.51
C	0.17	0.25
D	4.80	5.00
D1	1.50	3.50
E	3.80	4.00
E1	1.0	2.55
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
θ	0°	8°

● SOP-8 PACKAGE OUTLINE DRAWING


- Note: 1. Refer to JEDEC MS-012AA.
 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side .
 3. Dimension "E" does not include inter-lead flash or protrusions.
 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

SYMBOL	SOP-8	
	MILLIMETERS	
	MIN.	MAX.
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BSC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
θ	0°	8°

Note:

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